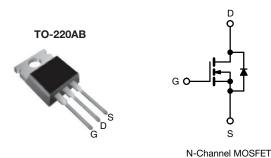




Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	200			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	1.5		
Q _g max. (nC)	8.2			
Q _{gs} (nC)	1.8			
Q _{gd} (nC)	4.5			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF610PbF		
Lead (Pb)-free and halogen-free	IRF610PbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	200	V	
Gate-source voltage			V_{GS}	± 20]	
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C		3.3		
		T _C = 100 °C	I _D	2.1	A	
Pulsed drain current ^a			I _{DM}	10		
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy b			E _{AS}	64	mJ	
Repetitive avalanche current ^a			I _{AR}	3.3	А	
Repetitive avalanche energy ^a			E _{AR}	3.6	mJ	
Maximum power dissipation	T _C =	25 °C	P_{D}	36	W	
Peak diode recovery dV/dt ^c			dV/dt	5.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	- °C	
Soldering recommendations (peak temperature) d	For	10 s		300		
Maria Para Laura	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 8.8 mH, R_g = 25 Ω , I_{AS} = 3.3 A (see fig. 12)
- c. $I_{SD} \le 3.3$ A, $dI/dt \le 70$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	3.5		

PARAMETER	SYMBOL	TEST	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0$	200	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.30	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	' _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zava gata valtaga dvaia avyvant	1	V _{DS} = 200 V, V _{GS} = 0 V		-	-	25	μΑ
Zero gate voltage drain current	$V_{DS} = 160 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$		/ _{GS} = 0 V, T _J = 125 °C	-	-	250	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 2.0 A ^b	-	-	1.5	Ω
Forward transconductance	9 _{fs}	V _{DS} = 5	0 V, I _D = 2.0 A ^b	0.8	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	140	-	pF
Output capacitance	C _{oss}			-	53	-	
Reverse transfer capacitance	C _{rss}			-	15	-	
Total gate charge	Qg		I _D = 3.3 A, V _{DS} = 160 V, see fig. 6 and 13 ^b	-	-	8.2	nC
Gate-source charge	Q _{gs}	V _{GS} = 10 V		-	-	1.8	
Gate-drain charge	Q_{gd}			-	-	4.5	
Turn-on delay time	t _{d(on)}			-	8.2	-	
Rise time	t _r	V_{DD} = 100 V, I_{D} = 3.3 A, R_{g} = 24 Ω , R_{D} = 30 Ω , see fig. 10 b		-	17	-	- ns
Turn-off delay time	t _{d(off)}			-	14	-	
Fall time	t _f			-	8.9	-	
Gate input resistance	Rg	f = 1 MHz, open drain		2.3	-	10.2	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	es	<u> </u>					
Continuous source-drain diode current	I _S	showing th	MOSFET symbol showing the		-	3.3	A
Pulsed diode forward current ^a	I _{SM}	integral reverse p - n junction diode		-	-	10	
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 3.3 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 3.3 A, dl/dt = 100 A/µs b		-	150	310	ns
Body diode reverse recovery charge	Q _{rr}			-	0.60	1.4	μC
Forward turn-on time	t _{on}	Intrinsic turn	-on time is negligible (turn	on is do	minated b	ov Ls and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

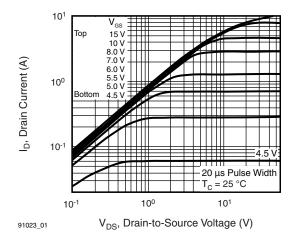


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

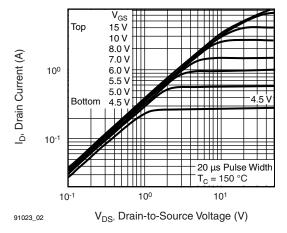


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

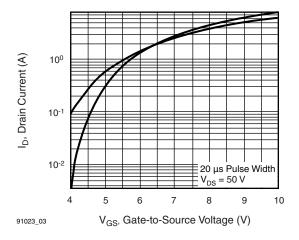


Fig. 3 - Typical Transfer Characteristics

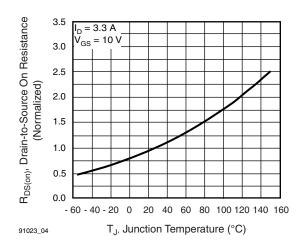


Fig. 4 - Normalized On-Resistance vs. Temperature

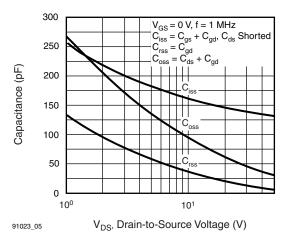


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

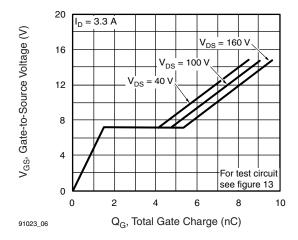


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



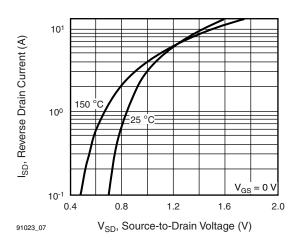


Fig. 7 - Typical Source-Drain Diode Forward Voltage

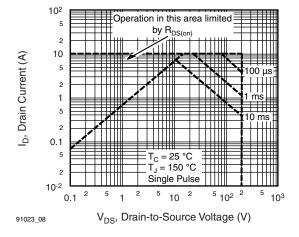


Fig. 8 - Maximum Safe Operating Area

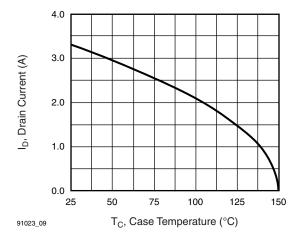


Fig. 9 - Maximum Drain Current vs. Case Temperature

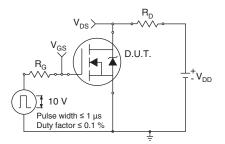


Fig. 10a - Switching Time Test Circuit

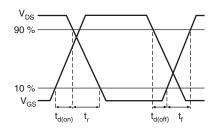


Fig. 10b - Switching Time Waveforms



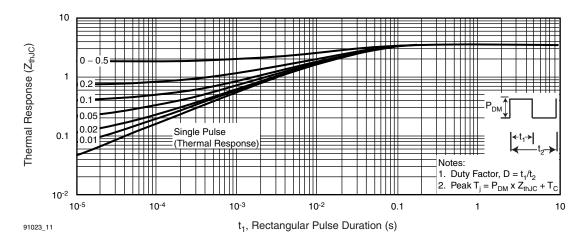


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

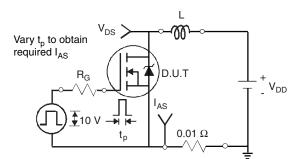


Fig. 12a - Unclamped Inductive Test Circuit

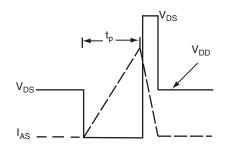


Fig. 12b - Unclamped Inductive Waveforms

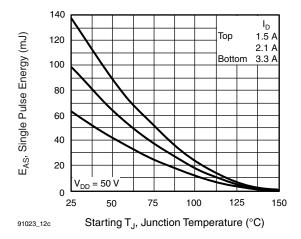


Fig. 12c - Maximum Avalanche Energy vs. Drain Current



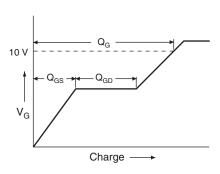


Fig. 13a - Basic Gate Charge Waveform

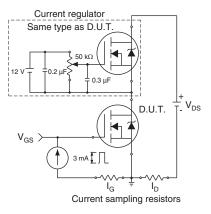
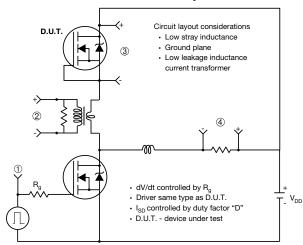


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



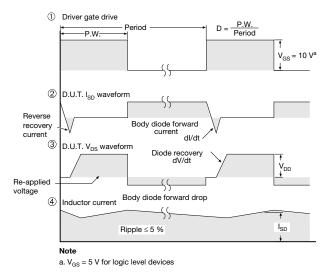


Fig. 14 - For N-Channel

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